



Materials Engineering Correlative Process- and Failure Analysis

We combine high resolution element analytic methods with surface & structure analysis methodologies and micro-mechanical characterisation to identify your process limits and to boost your innovation potential in respect to materials & processing R&D.

Structure analysis

- Spatially resolved crystal lattice analysis by **Electron BackScatter Diffraction**
- Phase analysis and texture measurement by **X-Ray Diffraction**
- Identification of chemical substances or functional groups by **Fourier Transform InfraRed Microscopy**

Surface Analysis

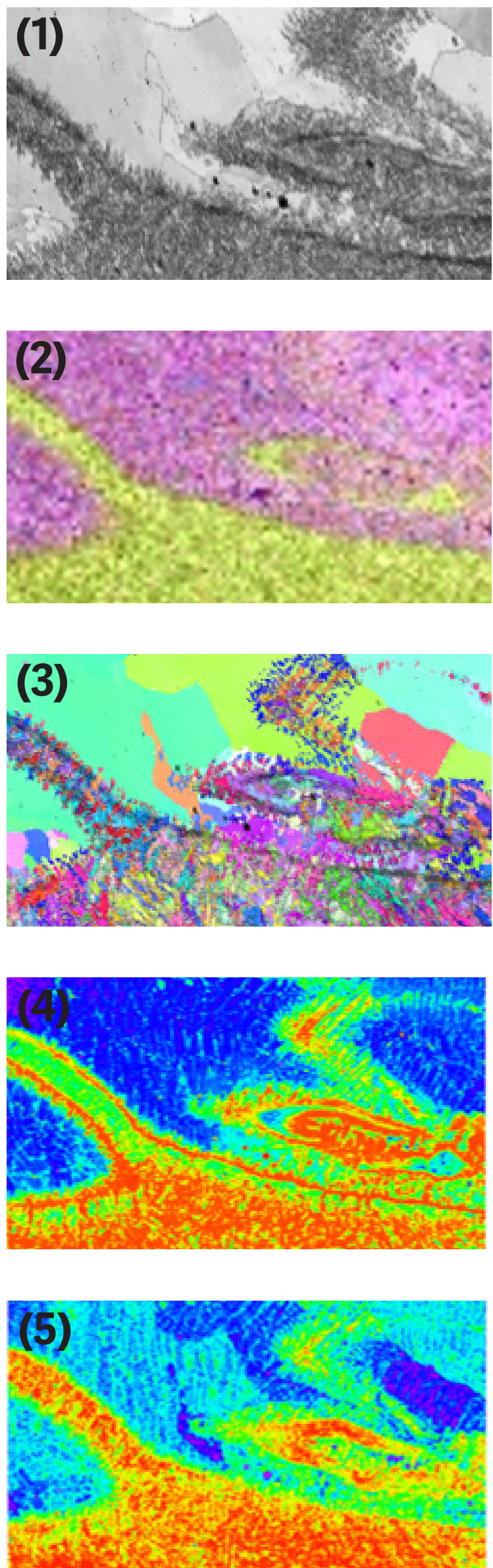
- Surface and fabric analysis by high resolution field emission **Scanning Electron Microscopy**

Micromechanical Testing

- Micro load-displacement experiments from mN to N in mode I/II/III
- Microhardness >2.5 mN

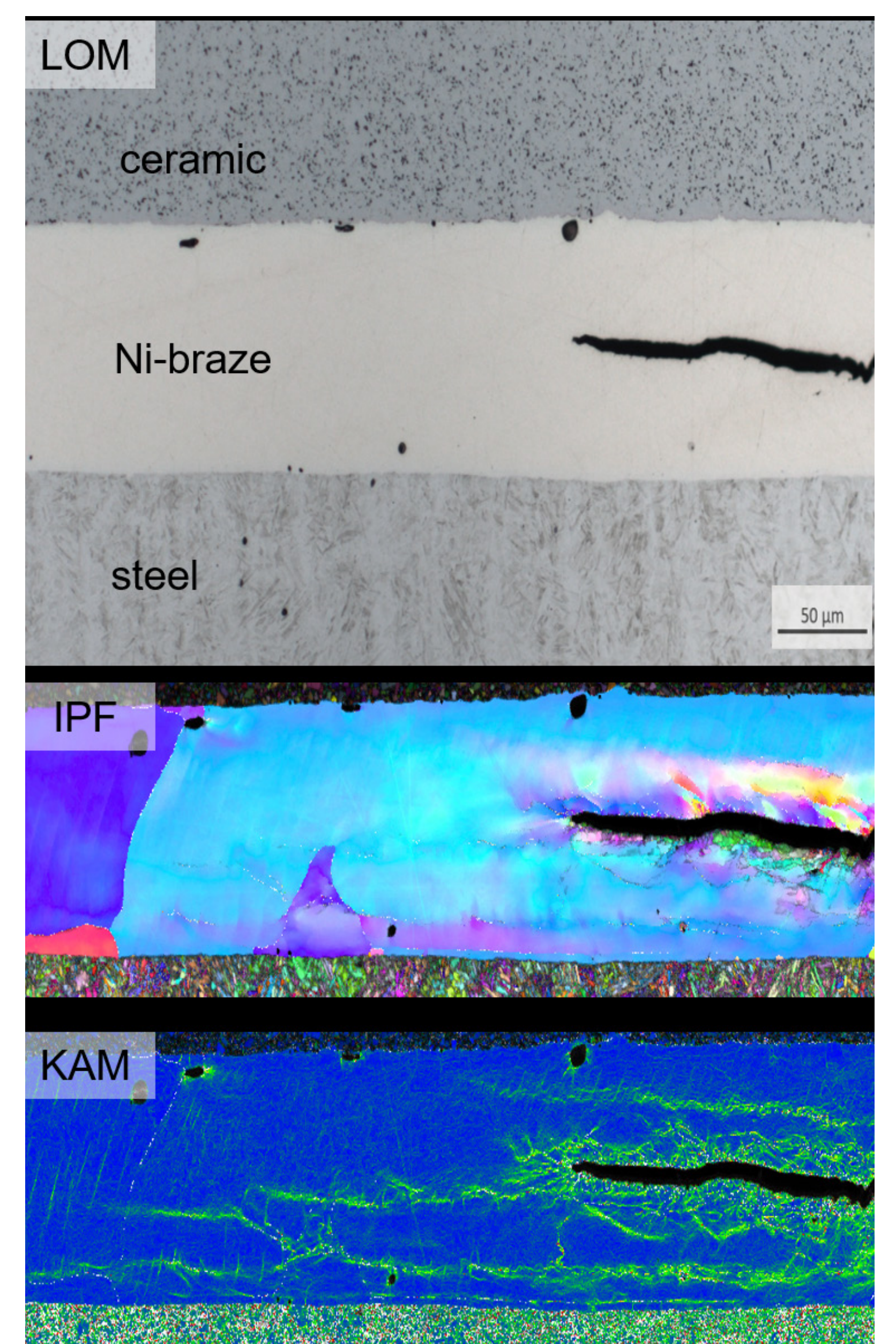
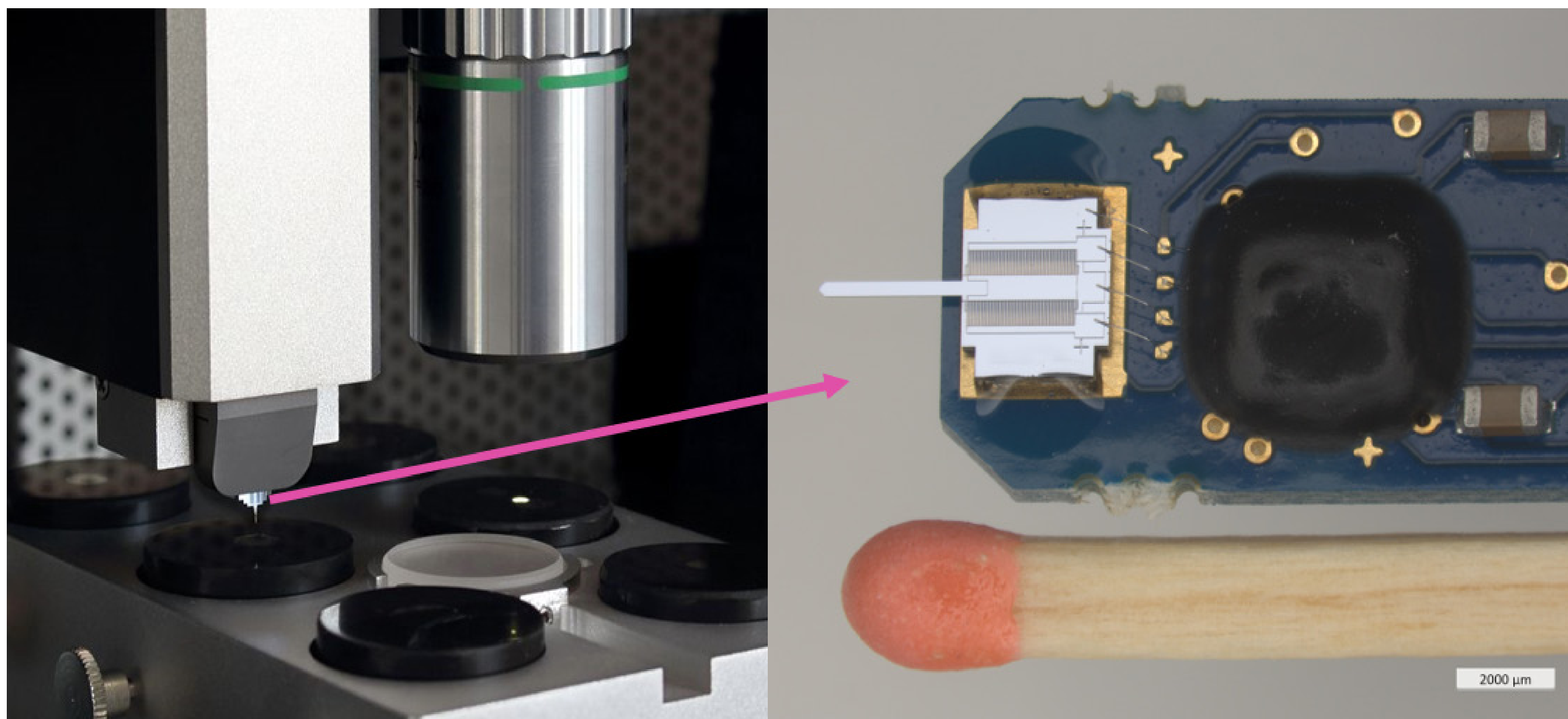
Element analysis

- Spatially resolved element analysis by **Electron Disperse X-ray** analysis.
- Quantitative element analysis of metal/alloy by **Optical Emission Spectroscopy**
- Quantitative element analysis by **X-Ray Fluorescence Spectroscopy**
- Quantitative analysis of organic compounds by **Gas Chromatography coupled Mass Spectrometry**



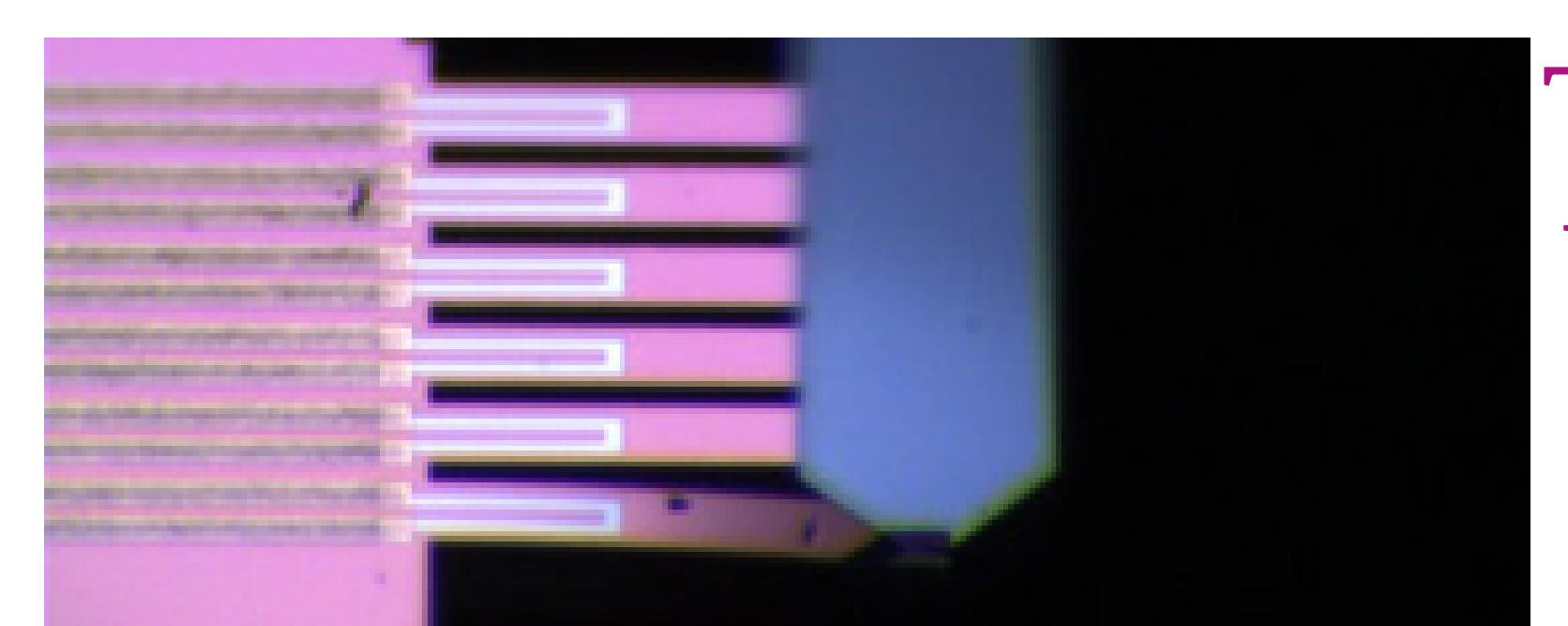
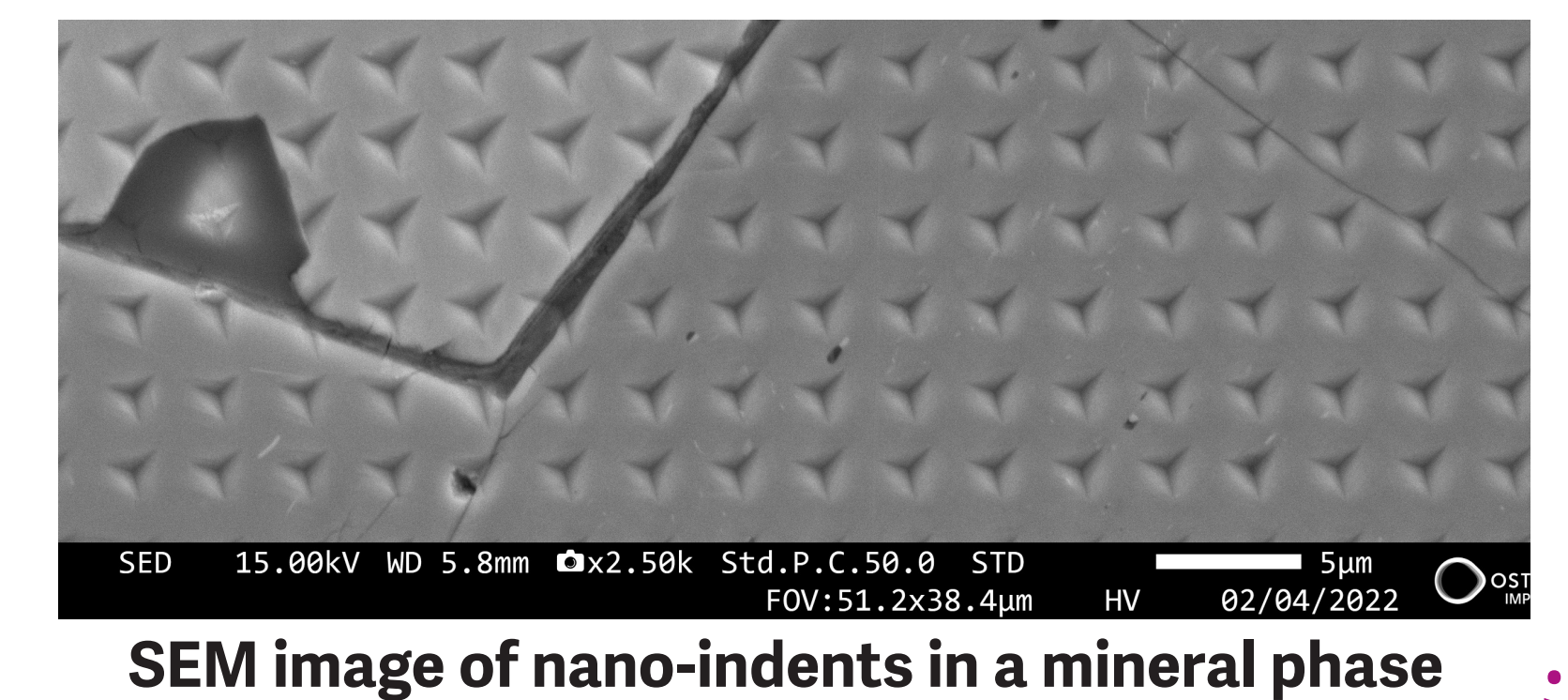
Imaging of a laser induced welding zone utilizing a correlative analysis approach:
(1) REM overview
(2) EDX element plot
(3) EBSD plot
(4) Hardness plot
(5) Young's modulus plot

Nano-indentation test setup (left) and detail of MEMS based nano-indenter showing the brazed indenter onto a MEMS force sensor (right).



Crack in solder joint visualized by optical light microscopy (LOM) and EBSD showing crystallographic misorientation (IPF) and strain distribution (KAM)

- Nanohardness by Nanoindentation up to 2 N
- Nano to micro fatigue testing from μN to mN in mode I/II/III



Cantilever fatigue test of microstructure by nano-indentation testing

